

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A manufacturing method for a three-dimensional structural body, comprising:

sequentially bonding/transferring and laminating a plurality of cross-sectional form members onto a second substrate, each cross-sectional form member being held in space above a first substrate by a holding member; and

and corresponding to a slice pattern of a three-dimensional structural body, onto a second substrate, releasing the cross-sectional form member from the holding member after the bonding/transferring and laminating.

2. (Currently Amended) The manufacturing method according to claim 1, wherein the bonding/transferring and laminating is performed using surface-activated bonding.

3. (Currently Amended) The manufacturing method according to claim 1, wherein the holding member comprises a coupling member connected to ~~the~~ a cross-sectional form member, and a frame member, ~~provided between the coupling member and the first substrate~~ wherein the first substrate is connected to the coupling member through the frame member.

4. (Original) The manufacturing method according to claim 3, wherein the frame member includes a columnar part provided on the first substrate, and a frame part provided on the columnar part and connected to the coupling member.

5. (Currently Amended) The manufacturing method according to claim 4, further comprising:

laminating a sacrificial layer and a material layer on the first substrate;

forming the cross-sectional form members, the frame part and the coupling member in the material layer; and

removing the sacrificial layer while a portion becoming the columnar part remains, and a gap occurs at least between the cross-sectional form members and the first substrate.

6. (Original) The manufacturing method according to claim 5, wherein the cross-sectional form members are formed by using a lithography method.

7. (Original) The manufacturing method according to claim 5, wherein the sacrificial layer is removed by using an under etching method.

8. (Currently Amended) The manufacturing method according to claim 3, wherein the coupling member is ruptured at a time of the bonding/transferring and laminating.

9. (Currently Amended) The manufacturing method according to claim 1, further comprising a collective of one or more cross-sectional form members, wherein the bonding/transferring and laminating is performed by causing the collective of cross-sectional form members to face the second substrate, and by sandwiching the collective of cross-sectional form members between the first substrate and the second substrate.

10. (Currently Amended) The manufacturing method according to claim 3, further comprising a collective of one or more cross-sectional form members, wherein the bonding/transferring and laminating is performed by causing the collective of cross-sectional form members to face the second substrate, and by sandwiching the collective of cross-sectional form members between the first substrate and the second substrate, and

the coupling member is ruptured after the collective of cross-sectional form members are transferred on the second substrate and when the second substrate is separated from the first substrate.

11. (Currently Amended) The manufacturing method according to claim 9, wherein a surface on the first substrate facing the collective of cross-sectional form members is flat.

12. (Currently Amended) The manufacturing method according to claim 10, wherein a surface on the first substrate facing the collective of cross-sectional form members is flat.

13. (Currently Amended) The manufacturing method according to claim 9, wherein a pressure to sandwich the collective of cross-sectional form members between the first substrate and the second substrate is applied to all of the ~~whole~~ cross-sectional form members of the collective.

14. (Currently Amended) The manufacturing method according to claim 10, wherein a pressure to sandwich the collective of cross-sectional form members between the first substrate and the second substrate is applied to all of the ~~whole~~ cross-sectional form members of the collective.

15. (Currently Amended) The manufacturing method according to claim 1, wherein the holding member comprises a first frame member positioned on the first substrate, a second frame member provided inside of the first frame member, a first coupling member connected to ~~the~~ a cross-sectional form member, and a second coupling member connecting the first and the second frame members.

16. (Currently Amended) The manufacturing method according to claim 15, wherein the second frame member and a ~~the~~ plurality of cross-sectional form members connected to the second frame member are simultaneously bonded and transferred onto the second substrate.

17. (Currently Amended) The manufacturing method according to claim 16, wherein the bonding/transferring and laminating is performed by causing the second substrate and the plurality of cross-sectional form members connected to the second frame member and the ~~second substrate~~ to face each other, and by sandwiching the second frame member and the plurality of cross-sectional form members between the first substrate and the second substrate.

18. (Original) The manufacturing method according to claim 1, wherein the three-dimensional structural body includes a photonic crystal having a periodic structure.